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TITLE: SUBSTRATE FOR MOUNTING SEMICONDUCTOR AND ITS PRODUCTION

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ABSTRACT:

PROBLEM TO BE SOLVED: To provide a substrate for mounting semiconductors having high joining strength of solder ball terminals and solder balls and a process for producing the same.

SOLUTION: This substrate for mounting the semiconductors is constituted by forming an electroless nickel plating film on a circuit consisting of metals, forming an electroless palladium plating film on the electroless nickel plating film and forming an electroless gold plating film on the electroless palladium plating film. The electroless nickel plating film is a nickel-boron alloy film. This process for producing the substrate for mounting the semiconductors consists in successively forming the electroless nickel-boron alloy plating, the electroless palladium plating and the electroless gold plating film on circuits consisting of metals, such as copper.

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